Call for Papers
2016 IEEE International Conference on Electron Devices and Solid-State Circuits
August 3-5, 2016
The University of Hong Kong
http://www.eee.hku.hk/edssc2016/

EDSSC 2016 is the 12th in a series of very successful conferences initiated by IEEE ED/SSC Hong Kong joint Chapter. After its great success in Singapore in 2015, EDSSC returns to Hong Kong this year. It is expected that the conference will be held in and outside Hong Kong in alternate years. EDSSC 2016 is a 3-day program consisting of broad areas in electron devices and solid-state circuits. Topics of interest include, but not limited to:

- Nanoelectronics
- Analog Circuits
- Memory Device and Technology
- Biomedical Circuits
- Thin Gate Dielectrics
- Data Conversion Circuits
- Photonic Devices
- Digital and Memory Circuits
- RF & Microwave Devices
- Power Management Circuits
- Power Devices
- RF & Microwave Circuits
- Sensors, imagers and MEMS
- Wireless and Wireline Communication Circuits
- Organic Devices
- Device Reliability
- Energy Efficient Devices
- Emerging Devices

Authors are requested to submit full papers in camera-ready form to the Technical Program Chair. Detail of submission will be given at the conference website in January 2016. All submissions must be in English and the works must be original and unpublished. The paper must be on A4-size paper (single-sided with 20-mm margin on all sides). Invited papers should not be more than 6 pages and regular papers should be 4-page long. Details of the paper format can be downloaded from the conference website in January 2016.

Important Dates:

- Submission Deadline: 01 April 2016
- Notice of Acceptance: 01 June 2016
- Early Registration by: 01 July 2016

Best Paper Awards
All regular papers will be considered for the best paper awards. The awards will be based on the technical content and presentation and one each for papers in the areas of electron devices and solid-state circuits.

Student Paper Contest
Student paper contest will also be held as part of the conference. Three prizes, i.e. first, second and third prizes will be awarded. Papers presented by full-time students and based on their own work will be considered for the competition. Qualified papers should be indicated at the time of submission.

Inquiry:
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- IEEE Solid-State Circuits Society
- IEEE Hong Kong Section
- Dept. of EEE, The University of Hong Kong

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